



## Features

- Processed with BCDMOS on SOI (Silicon on Insulator)
- Flexible High Voltage Supplies up to  $V_{PP}-V_{NN}=200V$
- Internal Output Bleed Resistors
- DC to 10MHz Analog Signal Frequency
- 60dB Minimum Output-Off Isolation at 5MHz
- Low Quiescent Power Dissipation ( $< 1\mu A$  Typical)
- Low Output On-Resistance
- Surface Mount Package

## Applications

- Ultrasound Imaging
- Printers
- Industrial Controls and Measurement
- Piezoelectric Transducer Drivers

## Description

The CPC7701 is a low charge injection 16-channel high-voltage analog switch integrated circuit (IC) for use in applications requiring high voltage switching. Bleed resistors are incorporated into both terminals of each output switch. Control of the high voltage switching is via low voltage CMOS logic level inputs for direct connectivity to the system controller.

Switch manipulation is managed by an 16-bit serial to parallel shift register whose outputs are buffered and stored by a 16-bit transparent latch. Level shifters buffer the latch outputs and operate the high voltage switches.

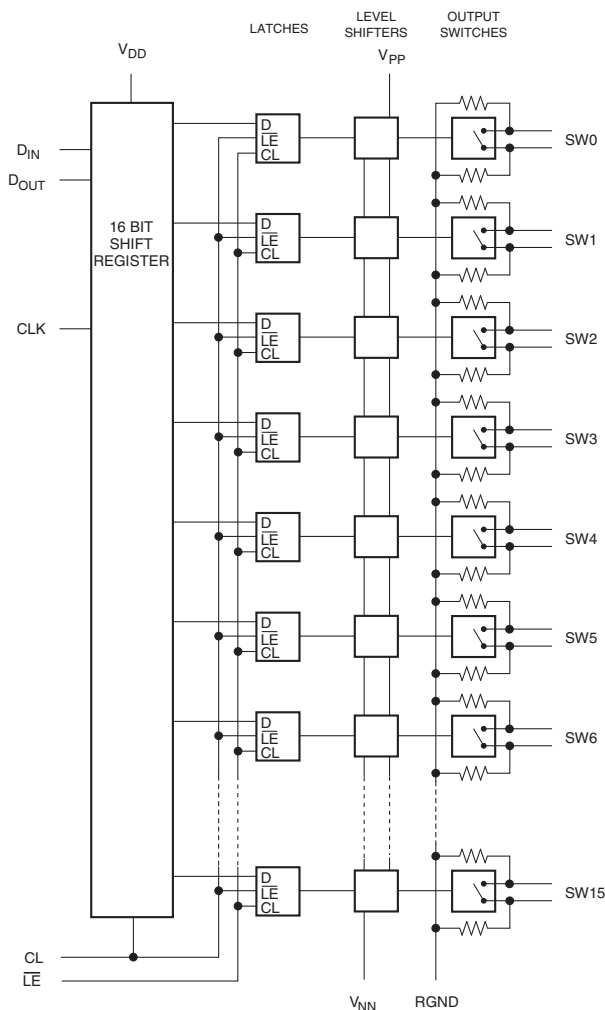
Because the CPC7701 is capable of switching high load voltages and has a flexible load voltage range, e.g.  $V_{PP}/V_{NN}$ : +40V/160V or +100V/100V, it is well suited for many medical and industrial applications such as medical ultrasound imaging, printers, and industrial measurement equipment. The bleed resistors enable the discharge of capacitive loads, such as piezoelectric transducers, connected to the output switches of the CPC7701.

Construction of the high voltage switches using IXYS Integrated Circuits Division's reliable SOI BCDMOS process technology allows the switches to be organized as solid state switches with direct gate drive.

## Ordering Information

Part Number	Description
CPC7701K	48-Pin LQFP in Trays (250/Tray)
CPC7701KTR	48-Pin LQFP Tape & Reel (2000/Reel)

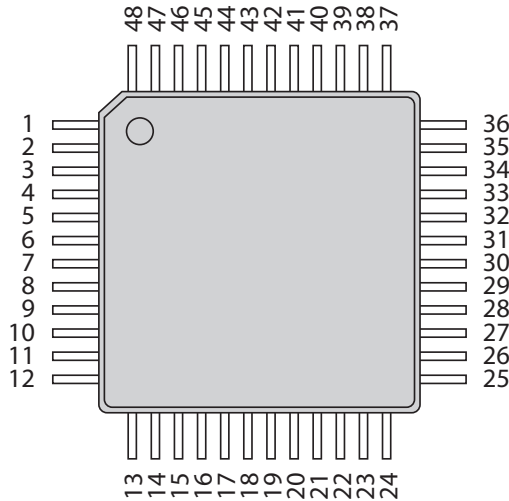
Figure 1. Block Diagram



<b>1. Specifications</b>	<b>3</b>
1.1 Package Pinout	3
1.2 Pin Description	3
1.3 Absolute Maximum Ratings	4
1.4 Operating Conditions	4
1.5 Electrical Characteristics	5
<b>2. Functional Description</b>	<b>8</b>
2.1 Truth Table	9
<b>3. Manufacturing Information</b>	<b>10</b>
3.1 Moisture Sensitivity	10
3.2 ESD Sensitivity	10
3.3 Reflow Profile	10
3.4 Board Wash	10
3.5 Mechanical Dimensions	11
3.6 Tape and Reel Specifications	11

## 1. Specifications

### 1.1 Package Pinout



### 1.2 Pin Description

Pin	Name	Description
3	SW4	SW4 Output
4	SW4	SW4 Output
5	SW3	SW3 Output
6	SW3	SW3 Output
7	SW2	SW2 Output
8	SW2	SW2 Output
9	SW1	SW1 Output
10	SW1	SW1 Output
11	SW0	SW0 Output
12	SW0	SW0 Output
13	V <sub>NN</sub>	Switch Negative High Voltage Supply
15	V <sub>PP</sub>	Switch Positive High Voltage Supply
17	GND	Ground: All Voltages are Referenced to Ground
18	V <sub>DD</sub>	Logic Positive Supply Voltage
19	D <sub>IN</sub>	Serial Data Input
20	CLK	Clock Input, Positive Edge Trigger
21	LE	Latch Enable, Active Low
22	CL	Latch Clear, Active High, Asynchronously Clears Latches and Opens Switches
23	D <sub>OUT</sub>	Serial Data Output
24	R <sub>GND</sub>	Ground for Bleed Resistors, Connect to GND
25	SW15	SW15 Output
26	SW15	SW15 Output
27	SW14	SW14 Output
28	SW14	SW14 Output
29	SW13	SW13 Output
30	SW13	SW13 Output
31	SW12	SW12 Output
32	SW12	SW12 Output
33	SW11	SW11 Output
34	SW11	SW11 Output
37	SW10	SW10 Output
38	SW10	SW10 Output
39	SW9	SW9 Output
40	SW9	SW9 Output
41	SW8	SW8 Output
42	SW8	SW8 Output
43	SW7	SW7 Output
44	SW7	SW7 Output
45	SW6	SW6 Output
46	SW6	SW6 Output
47	SW5	SW5 Output
48	SW5	SW5 Output
1, 2, 14, 16, 35, 36	N/C	No Connection

### 1.3 Absolute Maximum Ratings

Electrical Absolute Maximum ratings are at 25°C.

All voltages are referenced from ground (GND).

Parameter	Min	Max	Units
V <sub>DD</sub> Logic Power Supply Voltage	-0.5	7	V
V <sub>PP</sub> - V <sub>NN</sub> Supply Voltage	-	220	V
V <sub>PP</sub> Positive High Voltage Supply	-0.5	V <sub>NN</sub> +200	V
V <sub>NN</sub> Negative High Voltage Supply	-0.5	V <sub>PP</sub> -200	V
R <sub>GND</sub> -GND Differential	-0.3	+0.3	V
Logic input voltages	-0.5	V <sub>DD</sub> +0.3	V
Analog signal range	V <sub>NN</sub>	V <sub>PP</sub>	V
Peak analog signal current per channel	-	1	A
Power dissipation	-	2.3	W
Storage temperature	- 65	+150	°C

*Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.*

### 1.4 Operating Conditions

Parameter	Symbol	Value
Logic power supply voltage <sup>1</sup>	V <sub>DD</sub>	3V to 5.5V
Positive high voltage supply <sup>1</sup>	V <sub>PP</sub>	40V to V <sub>NN</sub> + 200V
Negative high voltage supply <sup>1</sup>	V <sub>NN</sub>	-40V to -160V
Analog signal voltage, peak-to-peak <sup>2</sup>	V <sub>SW</sub>	V <sub>NN</sub> +10V to V <sub>PP</sub> -10V
Operating temperature	T <sub>A</sub>	0°C to 70°C

<sup>1</sup> Power up/down sequence is arbitrary except that GND must be powered-up first and powered-down last.

<sup>2</sup> V<sub>SW</sub> must be V<sub>NN</sub> ≤ V<sub>SW</sub> ≤ V<sub>PP</sub> or floating during power up/down transition.

### 1.5 Electrical Characteristics

#### 1.5.1 Switch Characteristics (Over recommended operating conditions unless otherwise noted.)

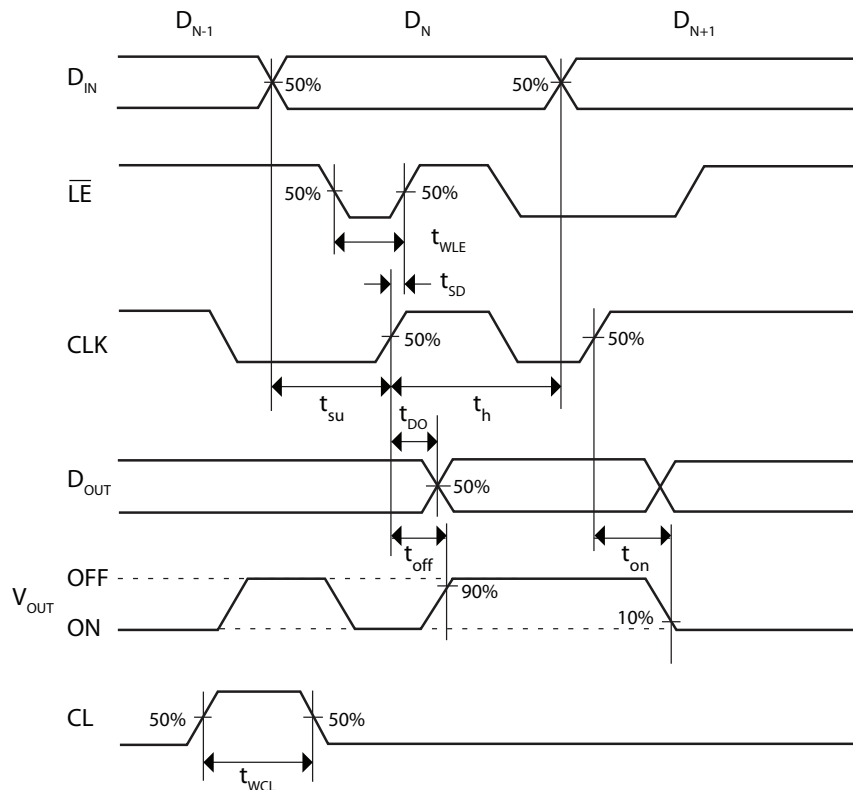
Parameter	Symbol	Test Conditions	0°C		+25°C			+70°C		Units	
			min	max	min	typ	max	min	max		
Switch on-resistance, Small signal	R <sub>ONS</sub>	V <sub>PP</sub> =40V, V <sub>NN</sub> =-160V	I <sub>SW</sub> =5mA	-	30	-	27	35	-	48	Ω
			I <sub>SW</sub> =200mA	-	26	-	22	29	-	40	
		V <sub>PP</sub> =100V, V <sub>NN</sub> =-100V	I <sub>SW</sub> =5mA	-	30	-	27	35	-	48	
			I <sub>SW</sub> =200mA	-	26	-	22	29	-	40	
		V <sub>PP</sub> =160V, V <sub>NN</sub> =-40V	I <sub>SW</sub> =5mA	-	30	-	27	35	-	48	
			I <sub>SW</sub> =200mA	-	26	-	22	29	-	40	
Switch on-resistance matching, Small signal	ΔR <sub>ONS</sub>	V <sub>PP</sub> =100V, V <sub>NN</sub> =-100V, I <sub>SW</sub> =5mA	-	20	-	4	20	-	20	%	
Switch on-resistance, Large signal	R <sub>ONL</sub>	V <sub>SW</sub> =V <sub>PP</sub> -10V, I <sub>SW</sub> =1A	-	-	-	15	-	-	-	Ω	
Output bleed resistors	R <sub>INT</sub>	Output switch to R <sub>GND</sub> , I <sub>RINT</sub> =0.5mA	-	-	20	28	50	-	-	kΩ	
Switch off leakage, per switch*	I <sub>SOL</sub>	V <sub>SW</sub> =V <sub>PP</sub> -10V and V <sub>NN</sub> +10V	-	5	-	0.4	10	-	15	μA	
DC offset, switch off	V <sub>OS</sub>	No Load	-	300	-	-	300	-	300	mV	
DC offset, switch on	V <sub>OS</sub>	No Load	-	500	-	-	500	-	500		
Switch output peak current	I <sub>SW</sub>	V <sub>SW</sub> duty cycle = 0.1%	-	-	-	-	1	-	-	A	
Output switch frequency	f <sub>SW</sub>	Duty cycle = 50%	-	-	-	-	50	-	-	kHz	
Maximum V <sub>SW</sub> slew rate	dV/dt	V <sub>PP</sub> =160V, V <sub>NN</sub> =-40V	-	20	-	-	20	-	20	V/ns	
		V <sub>PP</sub> =100V, V <sub>NN</sub> =-100V									
		V <sub>PP</sub> =40V, V <sub>NN</sub> =-160V									
Off isolation	K <sub>O</sub>	f=5MHz, Z <sub>L</sub> =1kΩ    15pF load	30	-	30	-	-	30	-	dB	
		f=5MHz, R <sub>L</sub> =50Ω load	58	-	58	-	-	58	-		
Switch crosstalk	K <sub>CR</sub>	f=5MHz, R <sub>L</sub> =50Ω load	-60	-	-60	-	-	-60	-	dB	
Output switch isolation diode current	I <sub>ID</sub>	300ns pulse width, 2.0% duty cycle	-	300	-	-	300	-	300	mA	
Off capacitance, SW to GND	C <sub>SG(OFF)</sub>	V <sub>SW</sub> =0V, f=1MHz	5	17	5	-	17	5	17	pF	
On capacitance, SW to GND	C <sub>SG(ON)</sub>	V <sub>SW</sub> =0V, f=1MHz	25	50	20	-	50	25	50		
Output voltage spike	+V <sub>SPK</sub>	V <sub>PP</sub> =40V, V <sub>NN</sub> =-160V	R <sub>L</sub> =50Ω	-	-	-	150	-	-	mV	
	-V <sub>SPK</sub>										
	+V <sub>SPK</sub>	V <sub>PP</sub> =100V, V <sub>NN</sub> =-100V									
	-V <sub>SPK</sub>										
	+V <sub>SPK</sub>	V <sub>PP</sub> =160V, V <sub>NN</sub> =-40V									
	-V <sub>SPK</sub>										
Charge injection	Q	V <sub>PP</sub> =100V, V <sub>NN</sub> =-100V, V <sub>SW</sub> =0V	-	-	-	820	-	-	-	pC	

\* Does not include the leakage current contribution due to the bleed resistors.

1.5.2 Logic Timing Characteristics  
(Over recommended operating conditions unless otherwise noted.)

Parameter	Symbol	Test Conditions	0°C		+25°C			70°C		Units
			min	max	min	typ	max	min	max	
Setup time before $\overline{LE}$ rises	$t_{SD}$	-	150	-	150	-	-	150	-	ns
Time width of $\overline{LE}$	$t_{WLE}$	$V_{DD}=3V$	56	-	56	-	-	56	-	
		$V_{DD}=5V$	12	-	12	-	-	12	-	
Clock delay time to Data Out	$t_{DO}$	$V_{DD}=3V$	10	100	10	-	100	10	100	
		$V_{DD}=5V$	5	45	5	-	45	5	45	
Time width of CL	$t_{WCL}$	-	55	-	55	-	-	55	-	
Setup time, data to clock	$t_{su}$	$V_{DD}=3V$	21	-	-	21	-	21	-	
		$V_{DD}=5V$	7	-	-	7	-	7	-	
Hold time, data from clock	$t_h$	-	2	-	2	-	-	2	-	
Clock frequency	$f_{CLK}$	50% duty cycle, $f_{DATA} = 1/2 f_{CLK}$ , $V_{DD}=3V$	-	8	-	-	8	-	8	MHz
		50% duty cycle, $f_{DATA} = 1/2 f_{CLK}$ , $V_{DD}=5V$	-	20	-	-	20	-	20	
Clock rise and fall times	$t_r, t_f$	-	-	50	-	-	50	-	50	ns
Turn-on time	$t_{on}$	$V_{SW}=V_{PP}-10V, RL=10k\Omega$	-	5	-	-	5	-	5	$\mu s$
Turn-off time	$t_{off}$		-	5	-	-	5	-	5	

1.5.3 Logic Timing Waveforms



1.5.4 Logic DC Characteristics  
(Over recommended operating conditions unless otherwise noted.)

Parameter	Symbol	Test Conditions	0°C		+25°C			+70°C		Units
			min	max	min	typ	max	min	max	
D <sub>OUT</sub> source capability	V <sub>OH</sub>	I <sub>OUT</sub> = -400μA	-	-	V <sub>DD</sub> -0.7	V <sub>DD</sub> -0.1	-	-	-	V
D <sub>OUT</sub> sink capability	V <sub>OL</sub>	I <sub>OUT</sub> = +400μA	-	-	-	0.04	0.7	-	-	V
Input (Logic) capacitance	C <sub>IN</sub>	-	-	10	-	-	10	-	10	pF
Input, Logic high	V <sub>IH</sub>	-	0.9 V <sub>DD</sub>	-	0.9 V <sub>DD</sub>	-	-	0.9 V <sub>DD</sub>	-	V
Input, Logic low	V <sub>IL</sub>	-	-	0.1 V <sub>DD</sub>	-	-	0.1 V <sub>DD</sub>	-	0.1 V <sub>DD</sub>	V

1.5.5 Supply DC Characteristics  
(Over recommended operating conditions unless otherwise noted.)

Parameter	Symbol	Test Conditions	0°C		+25°C			+70°C		Units
			min	max	min	typ	max	min	max	
V <sub>PP</sub> quiescent supply current	I <sub>PPQ</sub>	All switches off All switches on, I <sub>SW</sub> =5mA	-	-	-	0.1	50	-	-	μA
V <sub>NN</sub> quiescent supply current	I <sub>NNQ</sub>	All switches off All switches on, I <sub>SW</sub> =5mA	-	-	-	-0.1	-50	-	-	μA
V <sub>PP</sub> operating supply current	I <sub>PP</sub>	V <sub>PP</sub> =40V, V <sub>NN</sub> =-160V	-	6.5	-	-	7	-	8	mA
		V <sub>PP</sub> =100V, V <sub>NN</sub> =-100V	-	4	-	-	5.5	-	5.5	
		V <sub>PP</sub> =160V, V <sub>NN</sub> =-40V	-	4	-	-	5	-	5.5	
V <sub>NN</sub> operating supply current	I <sub>NN</sub>	V <sub>PP</sub> =40V, V <sub>NN</sub> =-160V	-	6.5	-	-	7	-	8	mA
		V <sub>PP</sub> =100V, V <sub>NN</sub> =-100V	-	4	-	-	5.5	-	5.5	
		V <sub>PP</sub> =160V, V <sub>NN</sub> =-40V	-	4	-	-	5	-	5.5	
V <sub>DD</sub> average supply current	I <sub>DD</sub>	f <sub>CLK</sub> =5MHz, V <sub>DD</sub> =5V	-	4	-	-	4	-	4	mA
V <sub>DD</sub> quiescent supply current	I <sub>DDQ</sub>	-	-	10	-	0.03	10	-	10	μA

1.5.6 Thermal Characteristics

Parameter	Conditions	Symbol	Minimum	Typical	Maximum	Units
Thermal Resistance (Junction to Ambient)	Free Air	R <sub>θJA</sub>	-	-	53	°C/W

## 2. Functional Description

The CPC7701 takes a serial stream of input data along with a synchronous clock signal. As the clock transits from low to high, the data at the input of each shift register is shifted through from SR(n) to SR(n+1). A high data bit, a “1,” represents an ON switch; a low data bit, a “0,” represents an OFF switch. Data is input and shifted through the internal shift register until all sixteen shift register positions, SR0 through SR15, are in the desired state.

**D<sub>IN</sub>:** The data-in line presents data bits to the CPC7701 to be shifted through the internal shift register. The last bit into the shift register is the SW0 control bit.

**CLK:** The clock signal's rising edge is associated only with shifting data into and through the shift register.

**CL:** The clear line overrides all other inputs. When CL is high, the shift register is asynchronously cleared to all 0s and all latches are set low, which causes all output switches to be turned OFF immediately. When CL is low, all output switches remain in whatever state they are in, ON or OFF, in response to CLK, latch inputs, and the  $\overline{LE}$  signal.

**$\overline{LE}$ :** latch enable controls the state of the latches and the state of the sixteen switches. If  $\overline{LE}$  is high, then the latches do not change states, but retain their most recent status: either ON or OFF. With  $\overline{LE}$  high, input data and CLK have no effect on the state of the output switches. If  $\overline{LE}$  is low, then all latch outputs and their switch states follow the inputs from the shift register.  $\overline{LE}$  is overridden by CL: no matter what state  $\overline{LE}$  is in, CL clears the latches. See “**Truth Table**” on page 9. Note that holding  $\overline{LE}$  active while clocking in new data will cause the outputs to toggle with the shifting data.

**D<sub>OUT</sub>:** The data-out pin is the output of SR15. After sixteen clock pulses, the first bit of sixteen shifted input data bits is output at SR15, and appears on D<sub>OUT</sub>.

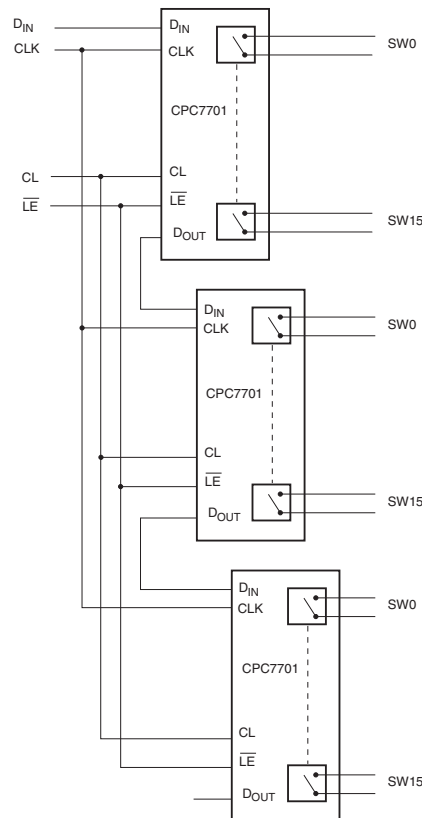
**SW0 - SW15:** The CPC7701 provides sixteen high-voltage SPST output switches with a nominal small signal on-resistance of 25Ω. The two connections of each switch are not polarity-sensitive. As can be seen in “**Block Diagram**” on page 1, integrated bleed resistors are provided to facilitate charge dissipation for capacitive load applications.

**V<sub>PP</sub> and V<sub>NN</sub>:** Voltage inputs to the level shifters for each switch channel that translate the voltage level of the latch output signals to an appropriate level for the voltages being switched.

The high-voltage output switches are turned on and off in response to the data sent into the latches from the shift register: data 0 turns a switch OFF, data 1 turns a switch ON.

Two or more CPC7701 devices can be cascaded to form an n-switch arrangement. The D<sub>OUT</sub> pin of the first is connected to the D<sub>IN</sub> pin of the next in the series. All devices are connected to the same clock (CLK) signal.  $\overline{LE}$  of all devices would normally be connected, as would CL, but this is not necessary.

The first data bit applied to D<sub>IN</sub> of the CPC7701, whether it's a single device or several cascaded devices, ripples through to the last switch output in line after the application of a full clocking sequence of 16 clock pulses. Setting the serial I/O device to output the most significant bit (MSB) first, results in the MSB appearing on SW15 of the last device in line after a full clocking sequence.







### 3. Manufacturing Information

#### 3.1 Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
CPC7701K	MSL 3

#### 3.2 ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

#### 3.3 Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

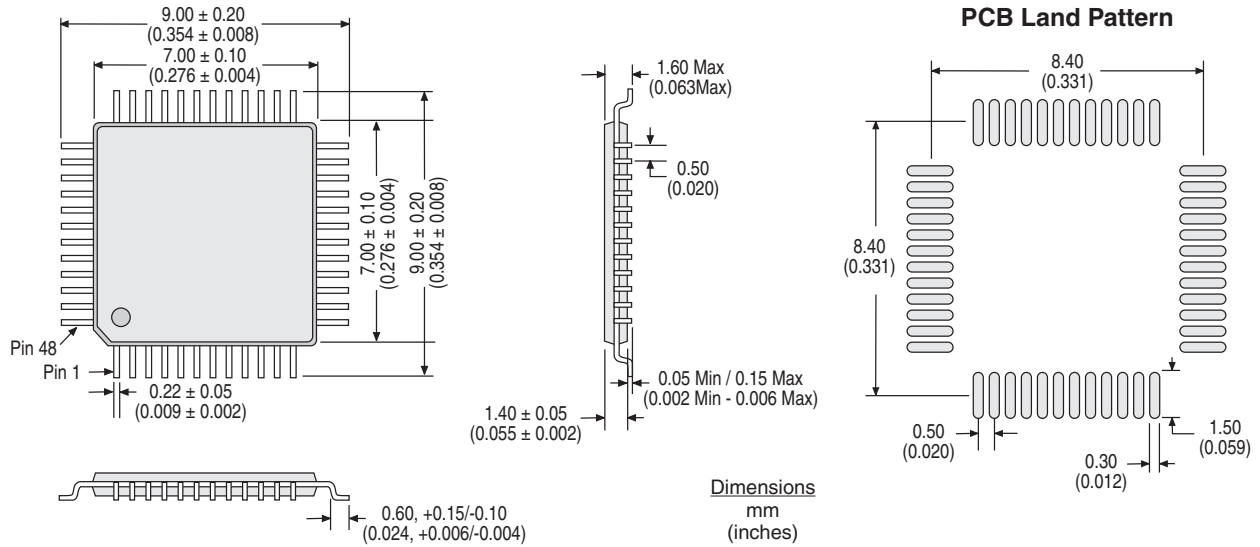
Device	Maximum Temperature x Time
CPC7701K	260°C for 30 seconds

#### 3.4 Board Wash

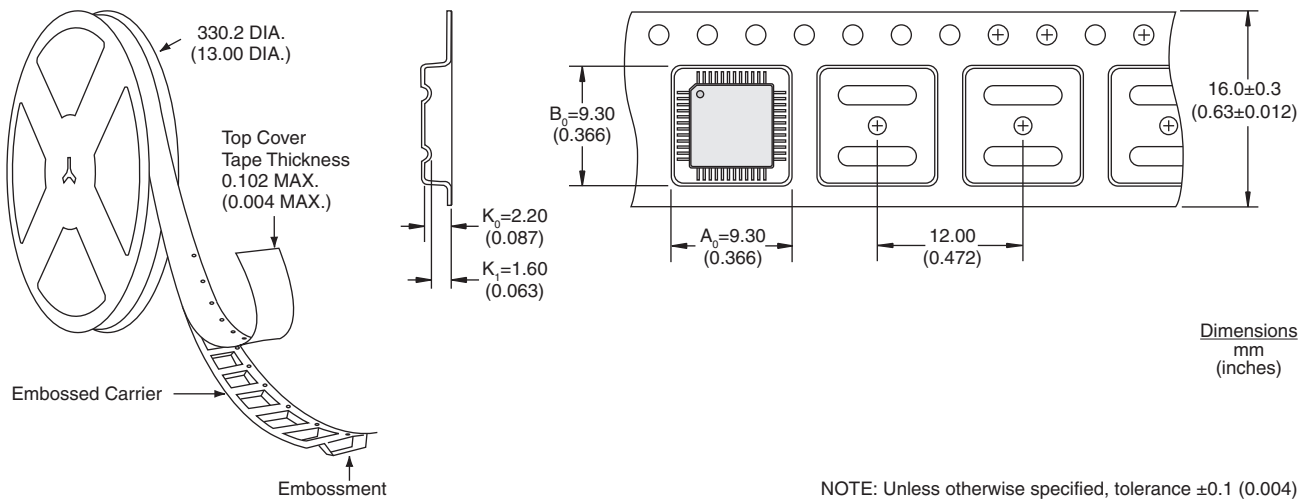
IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable, and the use of a short drying bake may be necessary. Chlorine-based or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.



### 3.5 Mechanical Dimensions



### 3.6 Tape and Reel Specifications



For additional information please visit [www.ixysic.com](http://www.ixysic.com)

IXYS Integrated Circuits Division makes no representations or warranties with respect to the accuracy or completeness of the contents of this publication and reserves the right to make changes to specifications and product descriptions at any time without notice. Neither circuit patent licenses or indemnity are expressed or implied. Except as set forth in IXYS Integrated Circuits Division's Standard Terms and Conditions of Sale, IXYS Integrated Circuits Division assumes no liability whatsoever, and disclaims any express or implied warranty relating to its products, including, but not limited to, the implied warranty of merchantability, fitness for a particular purpose, or infringement of any intellectual property right.

The products described in this document are not designed, intended, authorized, or warranted for use as components in systems intended for surgical implant into the body, or in other applications intended to support or sustain life, or where malfunction of IXYS Integrated Circuits Division's product may result in direct physical harm, injury, or death to a person or severe property or environmental damage. IXYS Integrated Circuits Division reserves the right to discontinue or make changes to its products at any time without notice.

Specification: DS-CPC7701-R03  
 © Copyright 2012, IXYS Integrated Circuits Division  
 All rights reserved. Printed in USA.  
 12/18/2012